

ABSTRACT OF THE DISCLOSURE

A multilayer wiring board having through holes in a thickness-wise direction, in which wiring board a semiconductor substrate mounted on the multilayer wiring board has through holes in a thickness-wise direction, and entire areas, which the through holes in the semiconductor substrate occupy, in a plane orthogonal to the thickness-wise direction of the multilayer wiring board and of the semiconductor substrate are included in areas, which the through holes in the multilayer wiring board occupy.

TOP SECRET